

1. General description

T Thyristor power switch in a TO92 plastic package with self-protective capabilities against low and high energy transients

2. Features and benefits

- Exclusive negative gate triggering
- Full cycle T conduction
- Very high noise immunity
- Remote gate separates the gate driver from the effects of the load current
- Safe clamping of low energy over-voltage transients
- Self-protective turn-on during high energy voltage transients
- High voltage capability

3. Applications

- Fan motor circuits
- Pump motor circuits
- Lower-power highly inductive, resistive and safety loads

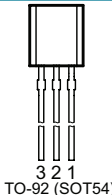
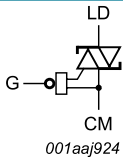
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Absolute maximum rating						
V_{DRM}	repetitive peak off-state voltage		-	-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 75\text{ °C}$; Fig 1 ; Fig 2 ; Fig 3	-	-	0.8	A
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; LD+ G-; $T_J = 25\text{ °C}$; Fig. 8	1	-	10	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; LD- G+; $T_J = 25\text{ °C}$; Fig. 8	1	-	10	mA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	CM	common		
2	G	gate		
3	LD	load		

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 75\text{ °C}$; Fig 1 ; Fig 2 ; Fig 3	-	0.8	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5	-	13	A
		full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$	-	14.3	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine-wave pulse	-	0.84	A ² s
di_T/dt	rate of rise of on-state current	$I_G = 20\text{ mA}$	-	100	A/ μ s
I_{GM}	peak gate current	$t_p = 20\text{ }\mu$ s	-	1	A
V_{GM}	peak gate voltage	positive applied gate voltage	-	15	V
$P_{G(AV)}$	average gate power	over any 20ms period	-	0.1	W
T_{stg}	storage temperature		-40	150	°C
T_j	junction temperature		-	125	°C
V_{PP}	peak pulse voltage	$T_j = 25\text{ °C}$; non-repetitive, off-state; ten pulses on each voltage polarity; 20s or more between successive pulses; Fig 6	-	2.5	kV

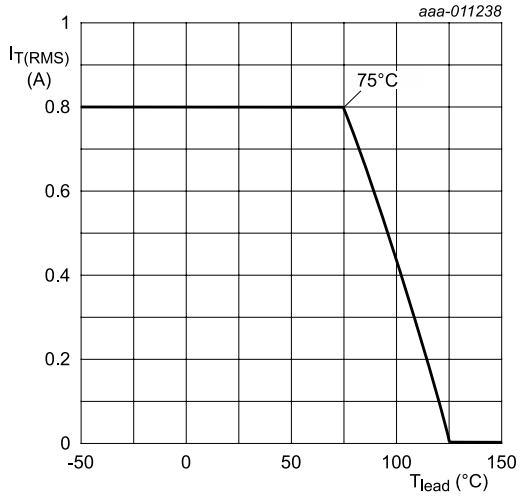
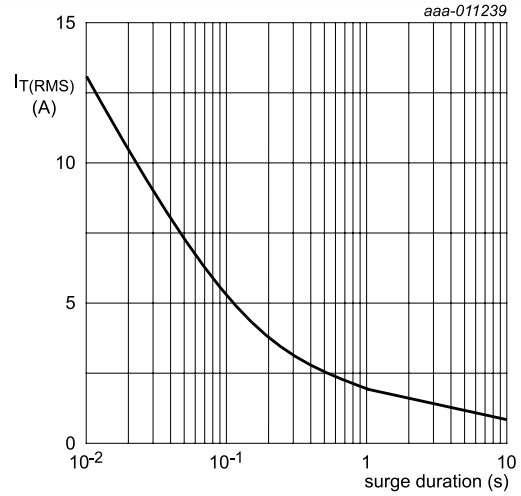
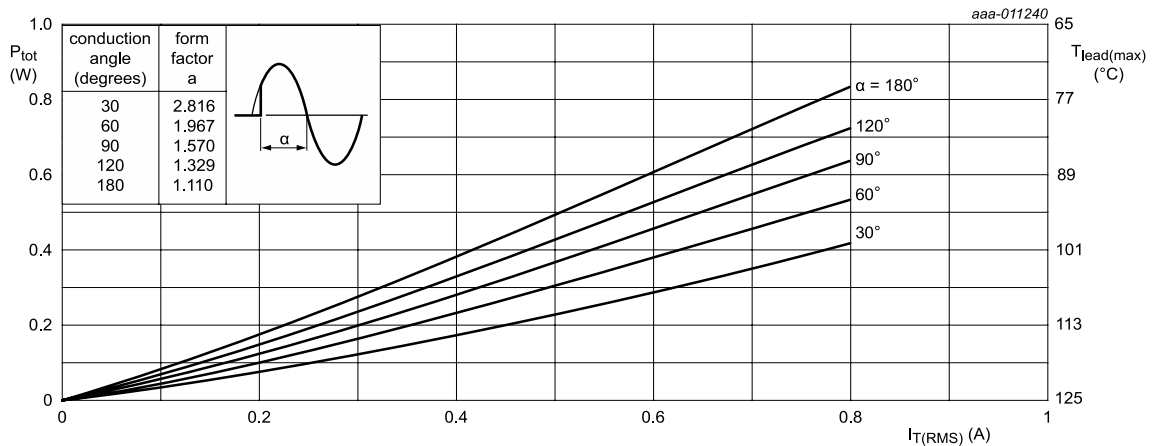


Fig. 1. RMS on-state current as a function of lead temperature; maximum values

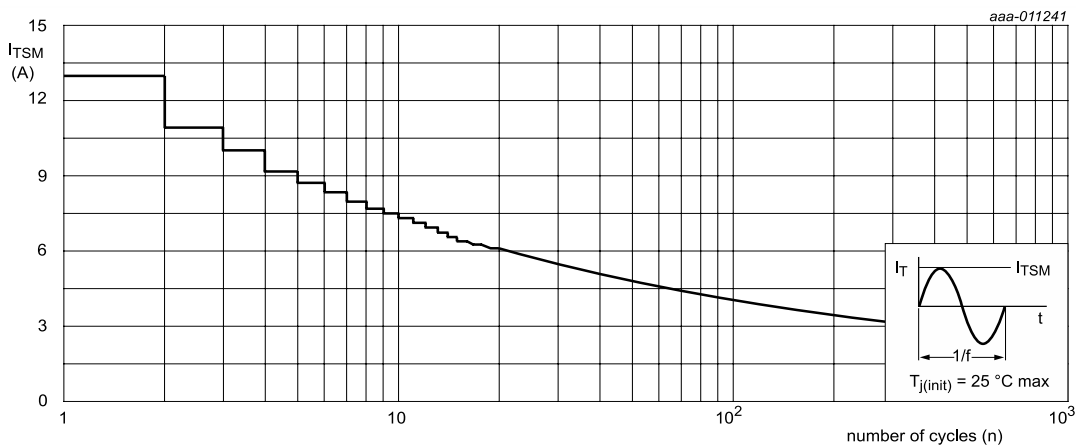


$f = 50 \text{ Hz}; T_{\text{lead}} = 75 \text{ }^\circ\text{C}$
Fig. 2. RMS on-state current as a function of surge duration; maximum values



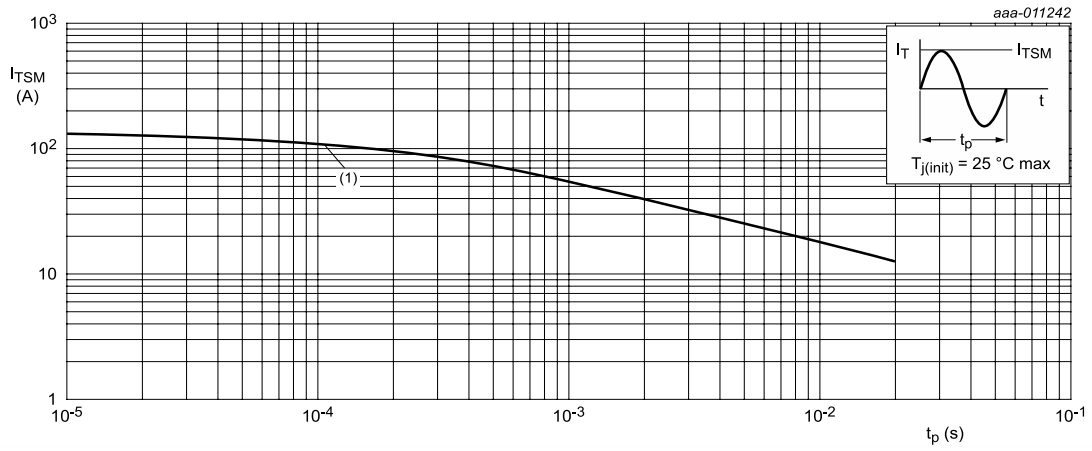
$\alpha = \text{conduction angle}$
 $a = \text{form factor} = I_{T(\text{RMS})}/I_{T(\text{AV})}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values



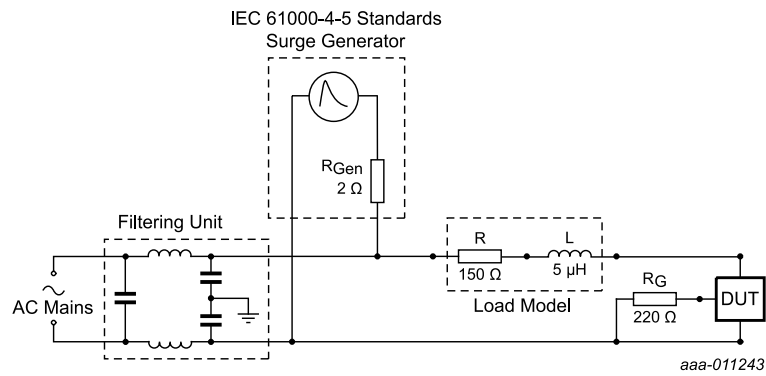
$f = 50 \text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 20\text{ ms}$
(1) dI_T/dt limit

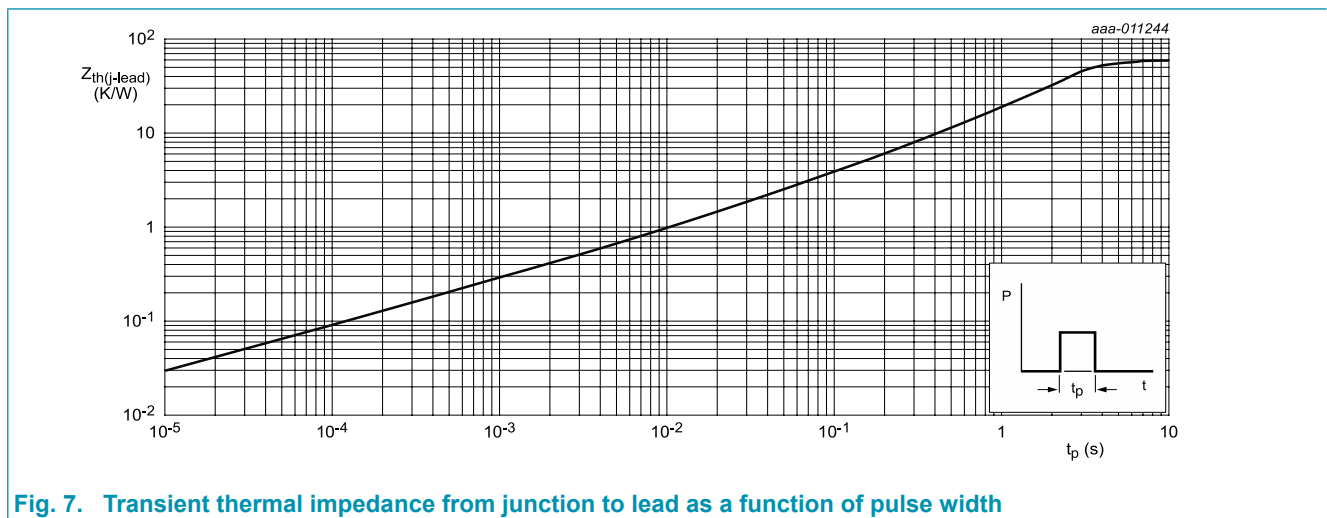
Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values



9. Thermal characteristics

Table 6. Thermal characteristics

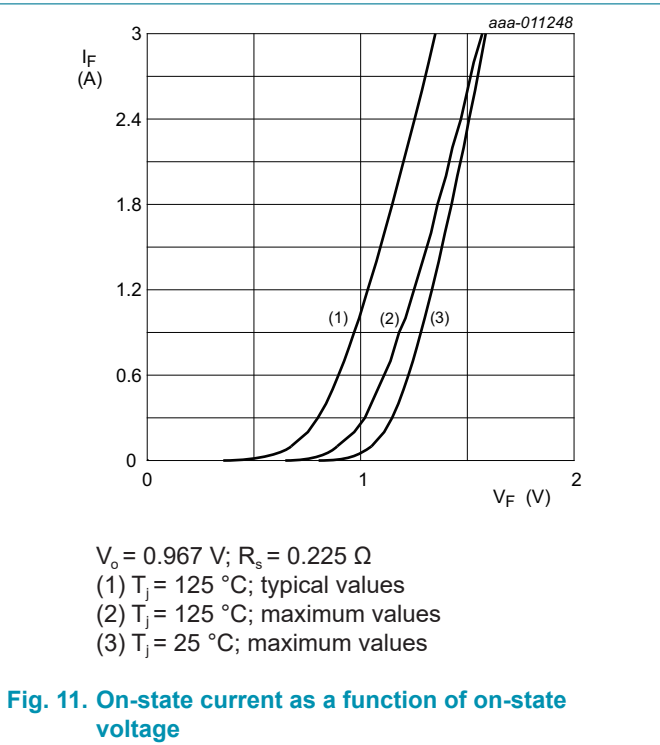
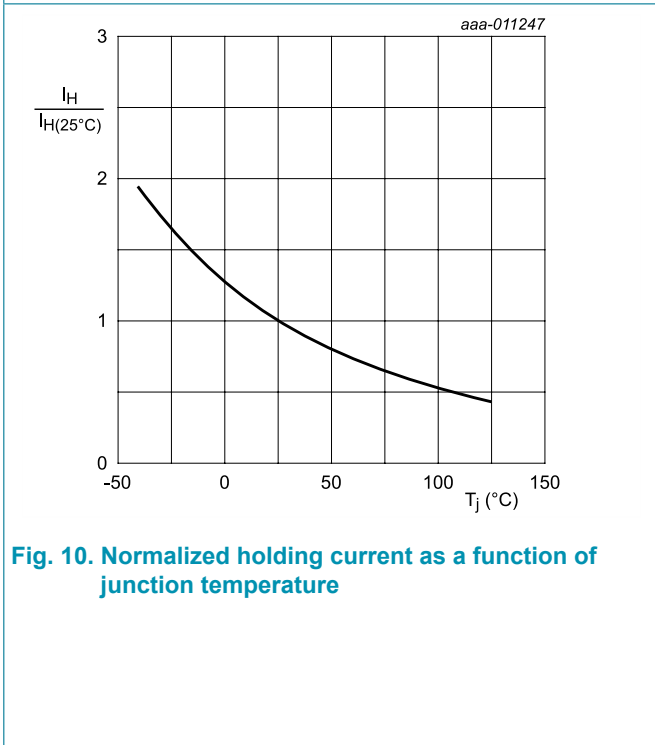
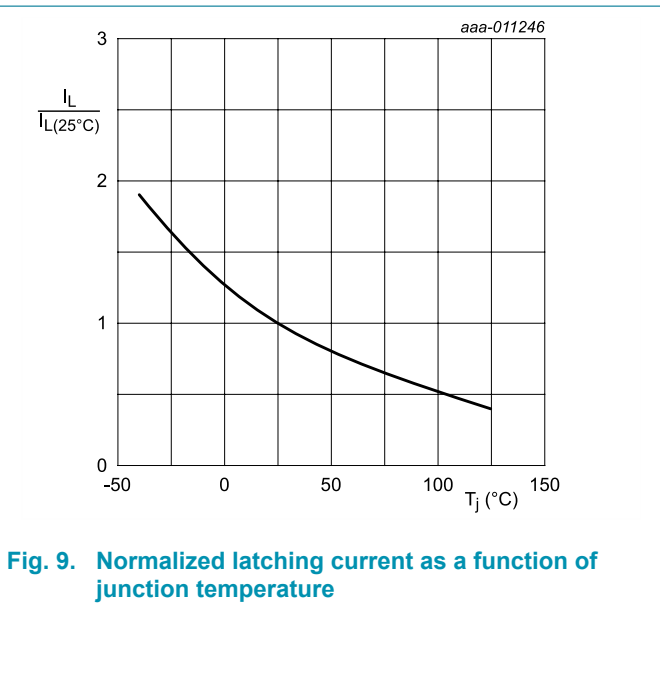
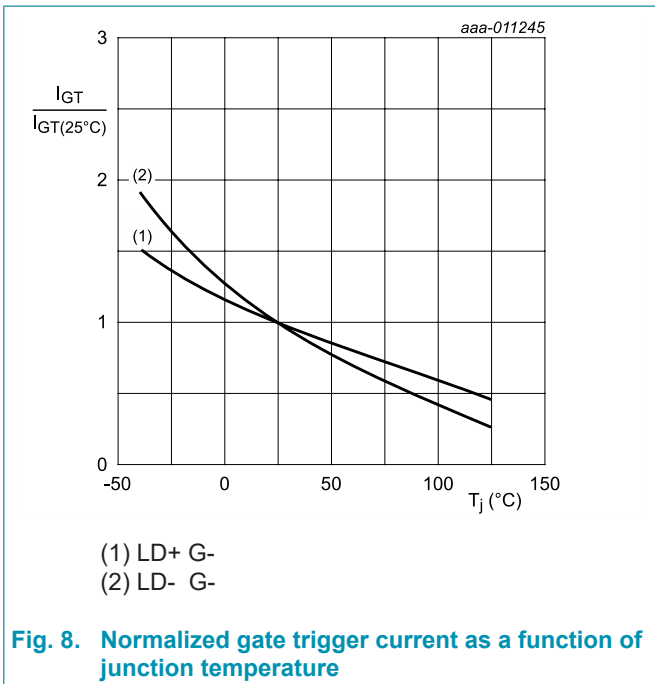
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	full cycle with heatsink compound; Fig. 7	-	-	60	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	full cycle; printed-circuit board mounted; lead length 4mm	-	150	-	K/W



T0. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; LD+ G-; T _J = 25 °C; Fig. 8	1	-	10	mA
		V _D = 12 V; I _T = 0.1 A; LD- G-; T _J = 25 °C; Fig. 8	1	-	10	mA
I _L	latching current	V _D = 12 V; I _G = 0.1 A; LD+ G-; T _J = 25 °C; Fig. 9	-	-	25	mA
		V _D = 12 V; I _G = 0.1 A; LD- G-; T _J = 25 °C; Fig. 9	-	-	20	mA
I _H	holding current	V _D = 12 V; T _J = 25 °C; Fig. 10	-	-	20	mA
V _T	on-state voltage	I _T = 1.1 A; T _J = 25 °C; Fig. 11	-	-	1.3	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _J = 25 °C; Fig. 12	-	-	1	V
		V _D = 400 V; I _T = 0.1 A; T _J = 125 °C	0.15	-	-	V
I _D	off-state current	V _D = 800 V; T _J = 25 °C	-	-	2	μA
		V _D = 800 V; T _J = 125 °C	-	-	0.2	mA
V _{CL}	clamping voltage	I _{CL} = 0.1 mA; t _p = 1 ms; T _J ≤ 25 °C;	850	-	-	V
Dynamic characteristics						
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 536 V; T _J = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit; Fig. 13	500	-	-	V/μs
dI _{com} /dt	rate of change of commutating current	V _D = 400 V; T _J = 125 °C; I _{T(RMS)} = 0.8 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit; Fig. 14 ; Fig. 15	0.5	-	-	A/ms



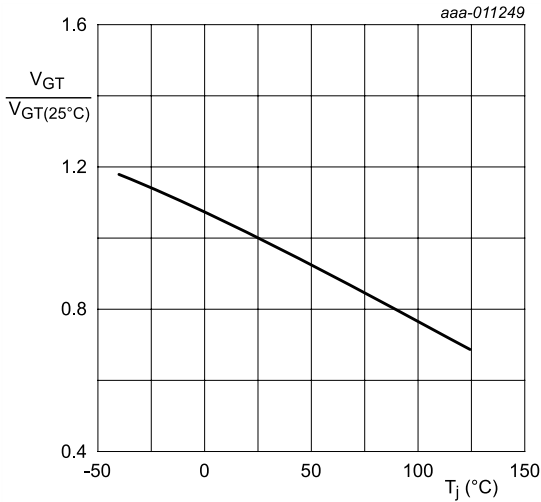
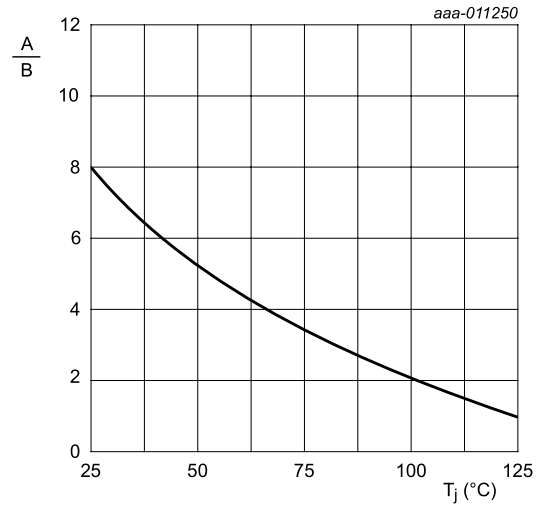
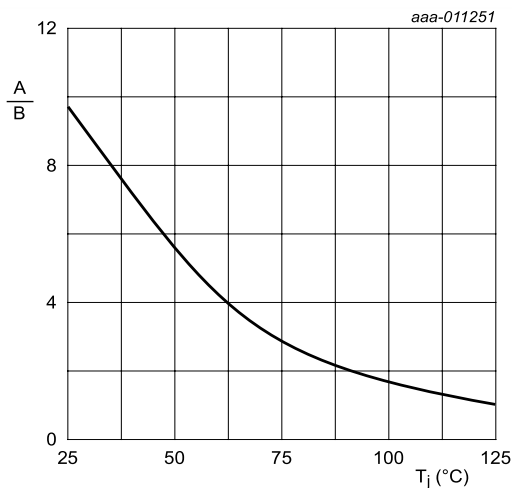


Fig. 12. Normalized gate trigger voltage as a function of junction temperature



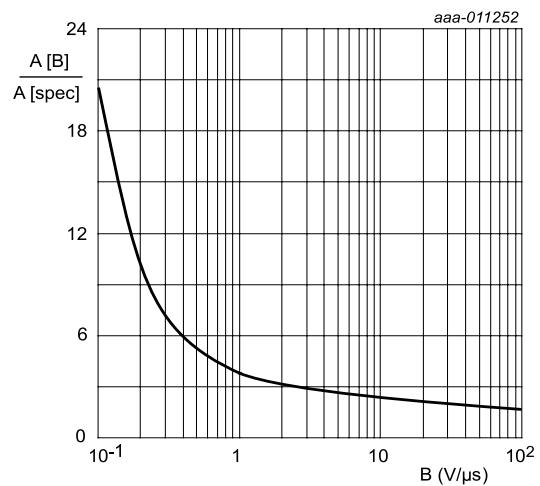
A = dV_D/dt at condition T_j °C
B = dV_D/dt at condition T_j [125] °C

Fig. 13. Normalized rate of rise of off-state voltage as a function of junction temperature



A = dI_{com}/dt at condition T_j °C
B = dI_{com}/dt at condition T_j [125] °C
 $V_D = 400$ V

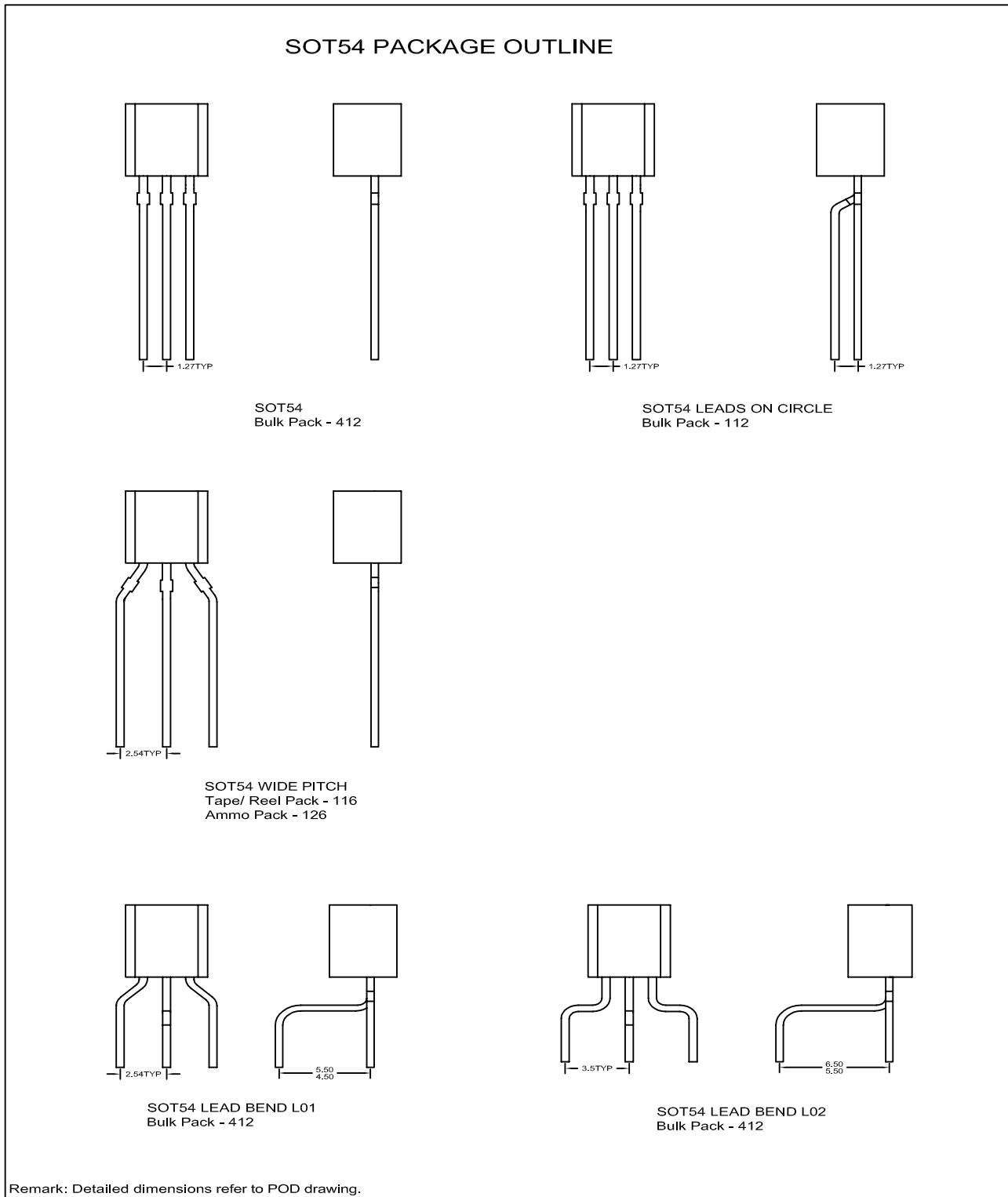
Fig. 14. Normalized critical rate of rise of commutating current as a function of junction temperature



A [B] = dI_{com}/dt at condition B, dV_{com}/dt
A [spec] is the data sheet value for dI_{com}/dt
turn-off time is less than 20 ms

Fig. 15. Normalized critical rate of change of commutating current as a function of critical rate of change of commutating voltage; minimum values

11. Package outline



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